

MPC859 to MPC8306/S Migration Guide

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1 Objective

The objective of this document is to serve as a guide for migrating MPC859 based designs to MPC8306/S based designs. It describes the differences between MPC859P/T/DSL and MPC8306/S, and recommends appropriate literature for further details.

2 References

MPC8306 PowerQUICC II Pro Integrated Host Processor Reference Manual

MPC8306 PowerQUICC II Pro Integrated Host Processor Hardware Specifications

MPC8306S PowerQUICC II Pro Integrated Host Processor Hardware Specifications

3 H/W Block Listing

[Table 1](#) gives a comparison of Hardware-blocks in both the SoCs.

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Table 1. List of IPs

IP	MPC859	MPC8306	MPC8306S
Core	MPC8x Max frequency 133 MHz	e300c3 Max frequency 333 MHz	e300c3 Max frequency 333 MHz
Cache	I-Cache – Upto 16KB D-Cache – Upto 8KB	I-Cache - 16KB D-Cache - 16KB	I-Cache - 16KB D-Cache - 16KB
DDR Controller	None	16-bit DDR2 SDRAM	16-bit DDR2 SDRAM
Communications Complex	Communications Processor Module – RISC controller with 8KB DPRAM and instruction ROM. 16 Serial DMA channels as part of CPM. 1 Serial Communication Controllers 2 Serial Management Controllers	QUICC Engine – RISC Controller with 48KB IRAM and 16KB MURAM; No ROM Independent Serial DMA channels 5 Unified Communication Controllers	QUICC Engine – RISC Controller with 48KB IRAM and 16KB MURAM; No ROM Independent Serial DMA channels 5 Unified Communication Controllers
UART	2 as part of SMC	2 Independent DUART Either 4 x two-wired Or 2 x four-wired	2 Independent DUART Either 4 x two-wired Or 2 x four-wired
I2C	1	2	2
SPI	1	1	1
GPIO	Parallel I/F port	Up to 56	Up to 56
JTAG	Present	Present	Present
PIC	Present	Present	Present
USB	None	1	1
External Bus Interface	32-bit non-multiplexed address bus and up to 32-bit data bus. Integrated DRAM controller with required external signals.	26-bit multiplexed address bus and 16-bit data bus with support for NAND FLASH	26-bit multiplexed address bus and 16-bit data bus with support for NAND FLASH
DMAC	2 x Independant DMA channels	Two DMA Engines – 1 x Sixteen channel and 1 x Four channel	Two DMA Engines – 1 x Sixteen channel and 1 x Four channel
Timers	4 x 16-bit or 2 x 32-bit general purpose WDT PIT	4 x 16-bit or 2 x 32-bit or 1 x 64-bit WDT PIT	4 x 16-bit or 2 x 32-bit or 1 x 64-bit WDT PIT
RTC	None	Present	Present
Ethernet	1 x 10/100Mbps MII 1 x 10Mbps (over SCC)	Upto 3 x 10/100Mbps MII/RMII (over UCC)	3 x 10/100Mbps MII/RMII (over UCC)
ATM	Over parallel UTOPIA L2 or Serial ATM over an SCC of CPM SAR and OAM functionality. Can operate simultaneously with 100Mbps Ethernet over MII.	None	None

Table 1. List of IPs

IP	MPC859	MPC8306	MPC8306S
PCMCIA-ATA	Master I/F with support for 2 independent sockets	None	None
eSDHC	None	Compatible with SDHC/MMC Std Ver 2.0 Clock frequency of 33.25 MHz with transfers @ upto 133 Mbps Block sizes upto 4KB 1-bit/4-bit SD and SDIO modes	None
FlexCAN	None	Present	None

4 Individual IP differences

Following sections cover differences on major IPs (which are present in both the devices).

4.1 Core

Table 2 provides a list of differences between MPC8xx and e300C3 cores

Table 2. Differences Between Cores

Feature	8xx (MPC859)	e300c3 (MPC8306/S)
PVR value	0x0050_00xx	0x8085_00xx
FPU support	Not Supported	Yes
MSR[FP]	RO always = 0 Always trigger FP unavailable exception (offset 0x800) if any FP instruction is executed	supported
MSR[FE0], MSR[FE1]	Not supported	supported
Performance Monitor support	No	Yes
Perf. Mon. exception	Not supported	Supported Offset 0xF00, belongs to async exception category w/ priority = 6 (lower than External Internal but higher than Decrementer Interrupt)
MSR[PMM]	Not supported	Supported To mark a process that will enable the statistics collection

Table 2. Differences Between Cores (continued)

Feature	8xx (MPC859)	e300c3 (MPC8306/S)
PMC0-3, UPMC0-3 Perf. Mon. Counter regs.	Not supported	Supported PMC0-3 are 32bit counters and UPMC0-3 (RO) are used by User level to read the counter values
PMGC0, UPMGC0 Perf. Mon. Global Control reg.	Not Supported	Supported PMGC0 provides global control for all the PM counters and UPMGC0 (RO) is used by User level to read the reg. value
PMLCa0-3, UPMLCa0-3 Perf. Mon. Local Control regs	Not Supported	Supported PMLCa0-3 provide local control to their corresponding PM counter and UPMLCa0-3 (RO) are used by User level to read the reg. value
mtpmr, mfpmr new instructions to move the data between PM cfg regs. and GPRs	Not Supported	Supported Functionally, mtpmr and mfpmr are similar to mtspr and mfspr except they apply on PM cfg regs. only while the latter apply to SPR regs.

4.2 DRAM Controller

MPC8306/S integrates a DDR2 SDRAM controller that supports a 16-bit interface @ 233 MHz, giving significant performance improvement over MPC859, which does not have a DDR SDRAM controller.

4.3 QUICC Engine

4.3.1 Differences in architecture

MPC8306/S does not have an internal ROM for storing the QUICC Engine RISC u-code. The u-code must be loaded into I-RAM from a non-volatile memory like EPROM/FLASH on-board by software, before using any QE functionality or interface. [Table 3](#) summarizes the hardware architecture differences between the Communication Processor Module and QUICC Engine on MPC859 and MPC8306/S respectively.

Table 3. QE H/W Differences

Hardware	MPC859	MPC8306/S QE
Internal ROM	Available	Not Available
I-RAM Size	8KB	48KB
MURAM Size	Not available	16KB
Number of UCC	None	5
Number of SCC	1	None

Table 3. QE H/W Differences

Hardware	MPC859	MPC8306/S QE
Number of SMC	2	None
Number of RISC	1	1
Number of SI	1	1
Max Frequency	133 MHz	233 MHz

4.3.2 Protocol support

Table 4 shows the comparison of QE interface/protocols supported by MPC859 and MPC8306/S.

Table 4. Interface/Protocols supported

Interface/Protocol	MPC859	MPC8306/S
MII	Supported	Supported
RMII	No	Supported
1588	No	Supported (not on MPC8306S)
ATM	Supported (Serial ATM only)	No
TDM	x6	x2
Async HDLC	Supported	Supported
SPI	Supported	No
Eth Management Interface	Supported	Supported
BISYNC	Supported	No
HDLC Bus	Supported	Supported
QMC	Supported	Supported
Transparent	Supported	Supported
Parallel I/O	Supported	No
I2C	Supported	No
Serial IrDA	Supported	No

4.4 External bus interface

4.4.1 Address/Data bus

The external bus interface on MPC859 provides non-multiplexed 32-bit address bus and data bus. MPC8306/S provides multiplexed 26-bit address bus and 16-bit data bus. An address latch device must be used outside the SOC to de-multiplex address signals [0:15] and data signals [0:15].

4.4.2 Clocks

MPC859 drives out a single CLKOUT signal, which directly sets the bus frequency. MPC8306/S drives out two LCLK signals that set the frequency of the external bus interface controller.

4.4.3 Modes of operation

The external bus interface controller on MPC859 supports two machines, General Purpose Chip-select Machine and User Programmable Machine.

The external bus interface controller on MPC8306/S supports Flash Control Machine in addition to GPCM and UPM. FCM facilitates a direct interface between NAND flash memory and SoC.

4.5 UART

MPC8306/S provides two DUART (DUART1 and DUART2). Each DUART has two 2-wire interfaces (RxD, TxD). Therefore, there are total four 2-wire interfaces.

Each DUART can also be configured as a single 4-wire interface (RxD, TxD, RTS, CTS). The 2-wire or 4-wire configuration can be done through programming the relevant fields of an SICR register. Refer to the section on signal multiplexing under the Software Changes section of this document.

4.6 Power Management

MPC859 supports two operational modes, i.e. Normal High and Normal Low. In Normal Low mode, all blocks within the device continue to operate normally, but at lower frequencies.

MPC8306/S supports four power states, i.e. Full Power, Doze, Nap and Sleep.

In Full Power mode, the e300 core and SOC operate normally.

In Doze mode, the e300 core stops dispatching new instructions and disables most of its functional units. However, the core time base and clocks continue to operate, with other functional blocks of the SOC.

In Nap mode, the core is stopped along with its clocks, except the time base. Other functional blocks of the SOC operate normally.

In sleep mode, the core along with its clocks and time base are stopped, except the interrupt unit. Other functional blocks of the SOC operate normally.

Refer to the Power Management Control section of the *MPC8306 PowerQUICC II Pro Integrated Host Processor Reference Manual* for further details and programming.

5 Software Changes

5.1 Tool-chain

e300c3 tool-chain should be used to compile the sources.

5.2 IDs

PVR (processor version register), SVR (system version register) and SPRIDR (System Part and Revision ID Register) registers show unique ID of any SoC. For MPC8306/S use following values.

PVR - 0x8085_00xx

SVR - 0x81100210

SPRIDR - 0x81100210

5.3 Reset Configuration Words

The main difference of Reset Configuration Words (RCW) is the core clock and QE PLL setting.

The Reset Configuration Word Low Register (RCWLR) and Reset Configuration Word High Register (RCWHR) for most common MPC8306/S systems are shown in [Table 5](#), [Table 6](#), and [Table 7](#).

SYS_CLK_IN at 33.33 MHz , Core clock @ 266 MHz, DDR clock @ 266 MHz, system bus @ 133 MHz and QE clock @ 200 MHz:

RCWLR - 0x4404_0006

Table 5. Reset Configuration Word Low Register (RCWLR) Example

LB C M	DDR C M	SV C O D	SPMF				—	CVC O D	CIMF				C F M F	—								CEV C O D	CE P D F	CEPMF				RCWLR
0	1	0 0	0 1 0 0	0 0	0 0	0 0	0 0	0 0 1 0	0 1	0 0 0 0 0 0 0 0	1 0	0 0 0 0 0 0 0 0	1 0	0 0 0 0 0 0 0 0	0 0	0 0 1 0	0	0 0 1 1 0	0x4405 0086									

Table 6. Individual Clock Frequency Description

Desc	SYS_CLK_IN	SVCO	SVCOD	XL B	LBI U	DDR	CVCO	Core	CEVCO	CEVCOD	CE
Freq(MHz)	33.33	533	266	133	133	266	533	266	400	200	200

Boot memory space (BMS) from 0x0000_0000 to 0x007F_FFFF, Local Bus 16-bit boot ROM:

Table 8. IPIC Vector Locations

Interrupt ID Number	Interrupt Meaning
34-37	Reserved
38	USB DR
39-41	Reserved
42	eSDHC (Not applicable for MPC8306S)
43-47	Reserved
48	IRQ0
49-63	Reserved
64	RTC SEC
65	PIT
66-67	Reserved
68	RTC ALR
69	Reserved
70	SBA
71	DMA Engine 2
72	GTM4
73	Reserved
74	QE Ports
75	GPIOx
76	DDRC
77	eLBC
78	GTM2
79	Reserved
80	PMC
81-83	Reserved
84	GTM3
85-89	Reserved
90	GTM1
91-93	Reserved
94	DMA Engine 1
95-127	Reserved

5.5 IMMR memory map

Table 9 defines the memory map of various IP within MPC8306/S.

Table 9. Memory Map

Block Base Address	Block	Actual Size	Window
0x0_0000–0x0_01FF	System configuration	512 bytes	512 bytes
0x0_0200–0x0_02FF	Watchdog timer	16 bytes	256 bytes
0x0_0300–0x0_03FF	Real time clock	32 bytes	256 bytes
0x0_0400–0x0_04FF	Periodic interval timer	32 bytes	256 bytes
0x0_0500–0x0_05FF	Global timers module 1	64 bytes	256 bytes
0x0_0600–0x0_06FF	Reserved	64 bytes	256 bytes
0x0_0700–0x0_07FF	Integrated programmable interrupt controller (IPIC)	128 bytes	256 bytes
0x0_0800–0x0_08FF	System arbiter	30 bytes	256 bytes
0x0_0900–0x0_09FF	Reset module	44 bytes	256 bytes
0x0_0A00–0x0_0AFF	Clock module	44 bytes	256 bytes
0x0_0B00–0x0_0BFF	Power management control module	20 bytes	256 bytes
0x0_0C00–0x0_0CFF	GPIO 1	24 bytes	256 bytes
0x0_0D00–0x0_0DFF	GPIO 2	24 bytes	256 bytes
0x0_0E00–0x0_12FF	Reserved		1.25 Kbytes
0x0_1300–0x0_13FF	QUICC Engine port interrupts		256 bytes
0x0_1400–0x0_17FF	Reserved		1 Kbyte
0x0_1800–0x0_1FFF	Reserved		2 Kbytes
0x0_2000–0x0_2FFF	DDR memory controller		4 Kbytes
0x0_3000–0x0_30FF	I2C controller 1		256 bytes
0x0_3100–0x0_31FF	I2C controller 2		256 bytes
0x0_3200–0x0_44FF	Reserved		4.75 Kbytes
0x0_4500–0x0_46FF	DUART1 (UART1 and UART2)		512 bytes
0x0_4700–0x0_48FF	Reserved		512 bytes
0x0_4900–0x0_4AFF	DUART2 (UART3 and UART4)		512 bytes
0x0_4B00–0x0_4FFF	Reserved		1.25 Kbytes
0x0_5000–0x0_5FFF	eLBC		4 Kbytes
0x0_6000–0x0_6FFF	Reserved		4 Kbytes
0x0_7000–0x0_70FF	SPI		256 bytes

Table 9. Memory Map

Block Base Address	Block	Actual Size	Window
0x0_7100–0x0_7FFF	Reserved		3.75 Kbytes
0x0_8000–0x0_82FF	DMA Engine 2		768 bytes
0x0_8300–0x2_83FF	Reserved		256 bytes
0x0_8400–0x0_84FF	I/O sequencer		256 bytes
0x0_8500–0x1_BFFF	Reserved		78.75 Kbytes
0x1_C000–0x1_CFFF	FlexCAN 1 (Reserved on MPC8306S)		4 Kbytes
0x1_D000–0x1_DFFF	FlexCAN 2 (Reserved on MPC8306S)		4 Kbytes
0x1_E000–0x2_2FFF	Reserved		20 Kbytes
0x2_3000–0x2_3FFF	USB DR (Device/ OTG)		4 Kbytes
0x2_4000–0x2_8FFF	Reserved		20 Kbytes
0x2_9000–0x2_9FFF	FlexCAN 3 (Reserved on MPC8306S)		4 Kbytes
0x2_A000–0x2_AFFF	FlexCAN 4 (Reserved on MPC8306S)		4 Kbytes
0x2_B000–0x2_BFFF	Reserved		4 Kbytes
0x2_C000–0x2_DFFF	DMA Engine 1		8 kbytes
0x2_E000–0x2_EFFF	eSDHC (Reserved on MPC8306S)		4 Kbytes
0x2_F000–0xE_FFFF	Reserved		772 Kbytes
0xF_0000–0xF_7FFF	On chip Boot ROM		32 Kbytes
0xF_8000–0xF_FFFF	Reserved		32 kbytes
0x10_0000–0x1F_FFFF	QUICC Engine		1 Mbytes
0x20_0000–0xFF_FFFF	Reserved		14 Mbytes

5.6 External Bus Controller

MPC8306/S supports port sizes 8-bit and 16-bit only.

NAND Flash control machine (FCM) mode, is not available on MPC859, but available on MPC8306/S, in addition to the GPCM and UPM machines.

The parity checking option is available only for FCM mode in MPC8306/S.

For booting from NAND Flash memory, RCWHR[ROMLOC] bit should be changed to 0b001 and RCWHR[RLEXT] bit should be changed to 0b01.

The external local bus interface of MPC8306/S has multiplexed address and data lines. The Options Register in MPC8306/S provides the option to add a delay for external address latching.

5.7 Signal Multiplexing

On MPC859, signal multiplexing selection is done through hard reset configuration, and through programming the SIUMCR and PPAR/PADIR registers.

On MPC8306/S, signal muxing selection is done through programming the System IO Configuration Registers. For details of the SICR registers, refer to the System Configuration section in the *MPC8306 PowerQUICC II Pro Integrated Host Processor Reference Manual*.

6 Hardware/Board Design considerations

6.1 Package and pin-out

MPC8306/S and MPC859 are not package and pin compatible. MPC8306/S is a 0.8mm pitch, 19mm x 19mm 369-MAPBGA device.

6.2 Clocking scheme

The clock inputs frequency specification changes are given in [Table 10](#).

Table 10. Clock Input Frequency

Clock Input	MPC859	MPC8306/S
XTAL-EXTAL	10 MHz to 10.66 MHz crystal	Not applicable
SYS_CLK_IN/EXTCLK	10 MHz to 10.66 MHz OR 45 MHz to 66 MHz	24 MHz to 66.67 MHz
RTC_PIT_CLOCK/PIT_CLK	Output from MPC859	32.768 kHz
QE_CLK_IN	Not applicable	24 MHz to 66.67 MHz

For detailed specifications of clocking on MPC8306/S, please refer to the Clocking and Clock Input Timing sections of the *MPC8306 PowerQUICC II Pro Integrated Host Processor Hardware Specifications* and *MPC8306S PowerQUICC II Pro Integrated Host Processor Hardware Specifications*.

6.3 Power Supply Specifications

[Table 11](#) summarizes the power rails of MPC859 and MPC8306/S.

Table 11. Power rails of MPC852 and MPC8306/S

Rail	MPC859	MPC8306/S
VDDL/VDD	1.7V to 1.9V	0.95V to 1.05V
VDDSYN/AVDD	1.7V to 1.9V	0.95V to 1.05V
VDDH/OVDD	3.165V to 3.465V	3.0V to 3.6V
GVDD	Not applicable	1.7V to 1.9V

GVDD refers to the DDR2 SDRAM interface power rail on MPC8306/S. This functionality is absent on MPC859.

NOTE

Signals of MPC8306/S are NOT 5V tolerant. Refer to the *MPC8306 PowerQUICC II Pro Integrated Host Processor Hardware Specifications* and *MPC8306S PowerQUICC II Pro Integrated Host Processor Hardware Specifications* document for the absolute maximum ratings of the device.

A typical power consumption estimate for MPC8306/S is given in [Table 12](#).

Table 12. Power Consumption Estimation

System Configuration e300 = 266 MHz QE = 200 MHz	DDR2 GV _{DD} Power (W)	NV _{DD} Power (W)	Core V _{DD} Power (W)	Total Power (W)
MPC8306/S 16-bit DDR2	0.14	0.15	0.45	0.74

Settings for estimation in [Table 12](#):

Typical Voltages (1.0V for Core VDD, 1.8V for GVDD, 3.3V for NVDD), Temperature at 25 oC ambient.

6.4 Reset Configuration Pins Changes

There are 4 reset source configuration pins for MPC8306/S. Since MPC8306/S supports NAND Flash boot up, there is a pin to either enable or disable ECC checking for NOR Flash during RCW load. [Table 13](#) provides all reset configuration signals changes.

Table 13. Reset Configuration Pins

Reset Configuration Signal	MPC8306/S
Configuration Reset Source	CFG_RESET_SOURCE[0:3]
Enable/Disable ECC for Flash during RCW load	LB_POR_CFG_BOOT_ECC
Status of ECC error during boot loading from flash	LBC_PM_REF_10 is an output signal which is not required to be configured.
Configuration clock in division selection	N/A
Selects multiplexing for address/data bus of the LBC block	N/A

6.5 Power supply sequencing

For MPC859, VDDL must not exceed VDDH during power-up and power-down.

For MPC8306/S, there is no specific requirement for application of individual power rails. In order to avoid driving IO pins, thus eliminating excessive current consumption, it is advisable to apply VDD and AVDD before applying GVDD and OVDD. Refer to the section on Power Sequencing in the *MPC8306 PowerQUICC II Pro Integrated Host Processor Hardware Specifications* and *MPC8306S PowerQUICC II Pro Integrated Host Processor Hardware Specifications*.

6.6 Pull-up pull-down Requirement for Miscellaneous Signals

Refer to the section on System Design Information in the *MPC8306 PowerQUICC II Pro Integrated Host Processor Hardware Specifications* and *MPC8306S PowerQUICC II Pro Integrated Host Processor Hardware Specifications*.

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